

Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 1 with the following amended paragraph:

--CROSS REFERENCE TO RELATED APPLICATIONS

This application is a divisional continuation of U.S. Patent Application entitled "Recognition Device, Bonding Device, and Method of Manufacturing a Circuit Device," filed 6/24/2002, Application Serial No. 10/178,506, now US Patent No. 6,715,660, which is incorporated herein by reference in its entirety.--

Please replace the paragraph beginning at page 15, line 18 with the following amended paragraph:

--Ring illumination 25 and lens barrel 29 shall now be described. Lens barrel 29 is disposed above ring illumination 25. Lead frame 34 and semiconductor elements 35, which are illuminated by ring illumination 25 via working hole 24, can be recognized by differences in reflectivity. By recognizing this reflected light by means of the recognition camera disposed inside lens barrel 29, pattern recognition of the upper side of lead frame 34 can be performed. Here, by using ring illumination 25 as the illumination, lead frame 34 and semiconductor elements 35 can be illuminated without bias and without giving rise to shadows, thereby enabling pattern recognition to be performed more precisely. Also, though though not illustrated, lens barrel 29 is bent in the middle at an angle of 90 degrees with respect to the surface of setting base 22 and the recognition camera is installed beyond this bent part. A mirror is installed an angle of 45 degrees with respect to the setting base 22 surface at this bent part, and pattern recognition can be performed by this structure.--

Please replace the paragraph on page 25, line 10 with the following amended paragraph:

--Pattern recognition of conductive foil 50, fixed on ~~heat~~ heating block 64, is then performed via working hole 24 and by means of the recognition camera inside lens barrel 29. After pattern recognition, thermocompression ball bonding and ultrasonic wedge bonding of the emitter electrodes of the respective mounting parts 55 inside block 52 to conductive pattern 41B and the base electrodes to conductive pattern 41B are performed as shown in Fig. 8.--

Please replace the paragraph on page 33, line 19 with the following amended paragraph:

--In this step, dicing blade 59 is preferably operated to a cutting depth at which insulating resin 40 is substantially severed and ~~ehocolate~~ breaking by a roller is performed after taking out block 52 from the dicing device. In the dicing process, the positioning marks 57, which were provided in advance in the above-described first step in a manner whereby they oppose each other at the inner sides of the frame-like pattern 56 that surrounds each block, are recognized and dicing is performed using these marks as reference. Though it is well known, for dicing, dicing in the longitudinal direction is performed along all dicing lines 58 and then the setting base is rotated by 90 degrees to perform dicing in the horizontal direction along dicing lines 58.--